Electronic Patent Application Fee Transmittal								
Application Number:	10723096							
Filing Date:	26-Nov-2003							
Title of Invention:	MOLDING COMPOUND							
First Named Inventor/Applicant Name:	John E. Kendall							
Filer:	Scott Chapple/Elise Nichols							
Attorney Docket Number:	62806A (1062-023)							
Filed as Large Entity								
Utility Filing Fees								
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)			
Basic Filing:								
Pages:								
Claims:								
Miscellaneous-Filing:								
Petition:								
Patent-Appeals-and-Interference:								
Post-Allowance-and-Post-Issuance:								
Utility Appl issue fee		1501	1	1400	1400			
Publ. Fee- early, voluntary, or normal		1504	1	300	300			

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
	Total in USD (\$)			1700